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STPS15L25D/G

LOW DROP POWER SCHOTTKY RECTIFIER

MAIN PRODUCT CHARACTERISTICS

I_{F(AV)}	15 A
V_{RRM}	25 V
T_{j (max)}	150 °C
V_{F (max)}	0.35 V

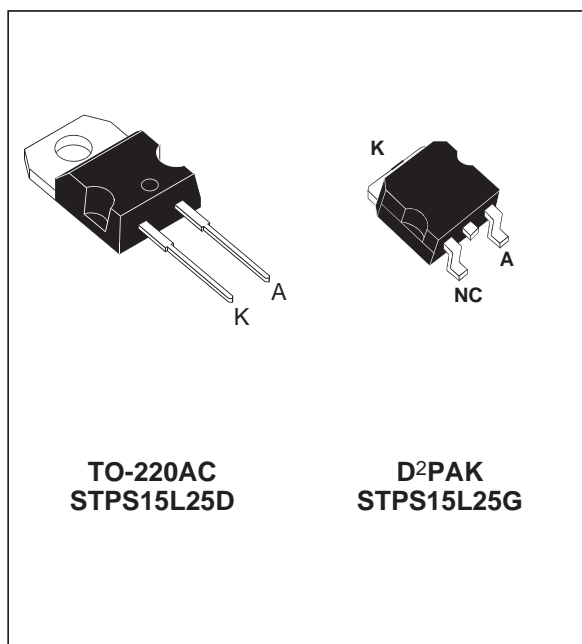
FEATURES

- VERY LOW FORWARD VOLTAGE DROP FOR LESS POWER DISSIPATION AND REDUCED HEATSINK
- OPTIMIZED CONDUCTION/REVERSE LOSSES TRADE-OFF WHICH MEANS THE HIGHEST EFFICIENCY IN THE APPLICATIONS
- AVALANCHE CAPABILITY SPECIFIED

DESCRIPTION

Single Schottky rectifier suited for Switched Mode Power Supplies and high frequency DC to DC converters (V_{RMS}).

Packaged in TO-220AC or D²PAK, this device is especially intended for use as a Rectifier at the secondary of 3.3V SMPS and DC/DC units.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
V _{RRM}	Repetitive peak reverse voltage		25	V
I _{F(RMS)}	RMS forward current		30	A
I _{F(AV)}	Average forward current	T _c = 145°C δ = 0.5	15	A
I _{FSM}	Surge non repetitive forward current	t _p = 10ms Sinusoidal	250	A
I _{RRM}	Repetitive peak reverse current	t _p = 2μs square F=1kHz	1	A
I _{RSM}	Non repetitive peak reverse current	t _p = 100μs square	4	A
P _{ARM}	Repetitive peak avalanche power	t _p = 1μs T _j = 25°C	9000	W
T _{stg}	Storage temperature range		- 65 to + 150	°C
T _j	Maximum operating junction temperature *		150	°C
dV/dt	Critical rate of rise of reverse voltage		10000	V/μs

* : $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j-a)}$ thermal runaway condition for a diode on its own heatsink

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THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	1	°C/W

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameters	Test conditions	Min.	Typ.	Max.	Unit
I_R *	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$		1.3	mA
		$T_j = 125^\circ\text{C}$		225	450	mA
V_F *	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 15\text{A}$		0.46	V
		$T_j = 125^\circ\text{C}$	$I_F = 15\text{A}$	0.3	0.35	
		$T_j = 25^\circ\text{C}$	$I_F = 30\text{A}$		0.56	
		$T_j = 125^\circ\text{C}$	$I_F = 30\text{A}$	0.41	0.46	

Pulse test : * $t_p = 380 \mu\text{s}$, $\delta < 2\%$

To evaluate the maximum conduction losses use the following equation :

$$P = 0.24 \times I_{F(AV)} + 0.0073 I_{F(RMS)}^2$$

Fig. 1: Average forward power dissipation versus average forward current.

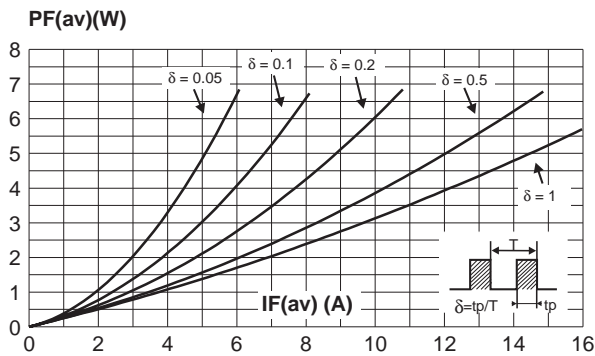


Fig. 3: Normalized avalanche power derating versus pulse duration.

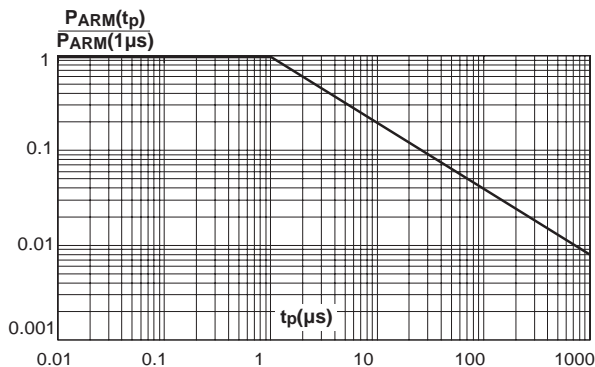


Fig. 2: Average forward current versus ambient temperature ($\delta = 0.5$).

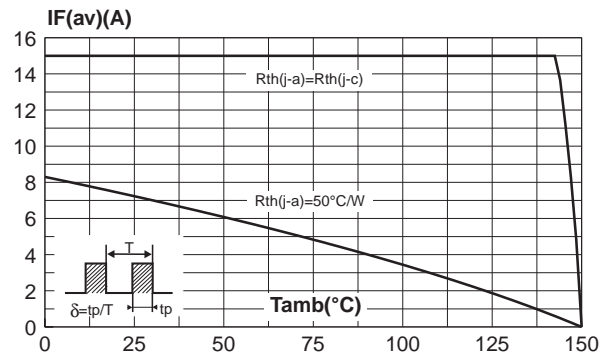
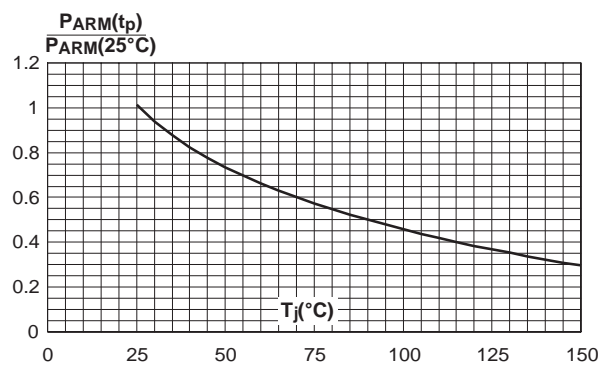


Fig. 4: Normalized avalanche power derating versus junction temperature.



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Fig. 5: Non repetitive surge peak forward current versus overload duration (maximum values).

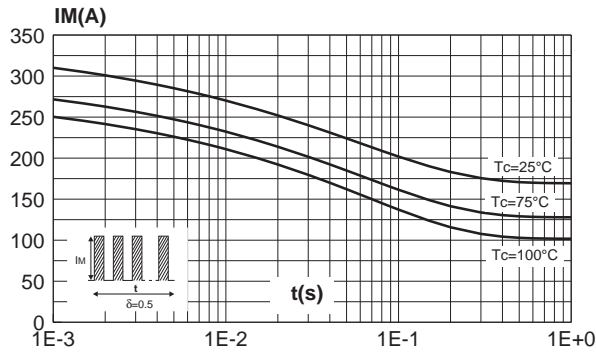


Fig. 6: Relative variation of thermal impedance junction to case versus pulse duration.

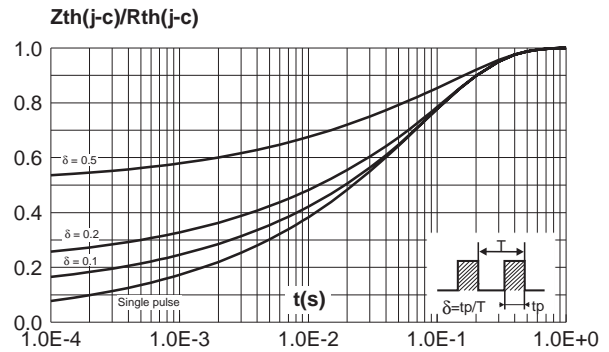


Fig. 7: Reverse leakage current versus reverse voltage applied (typical values).

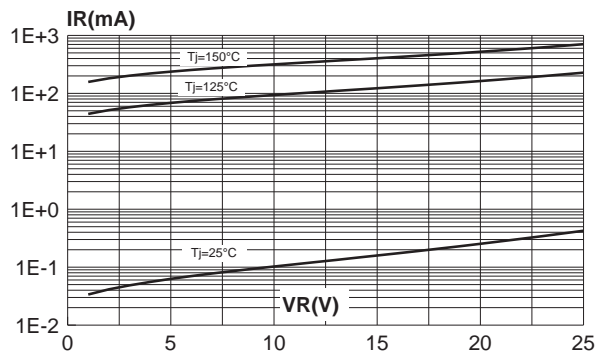


Fig. 8: Junction capacitance versus reverse voltage applied (typical values).

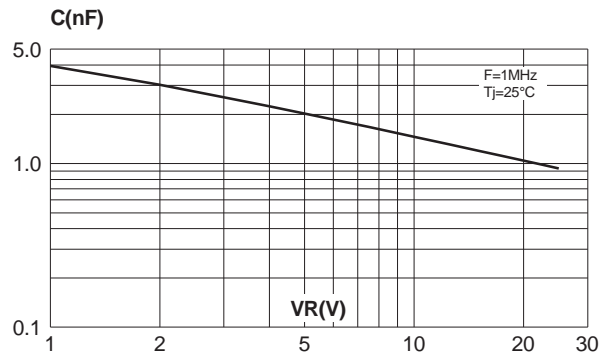


Fig. 9: Forward voltage drop versus forward current (maximum values).

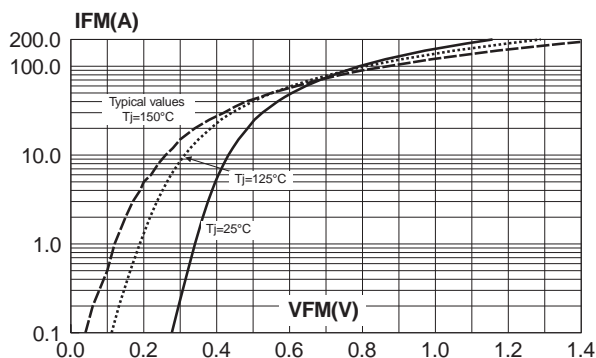
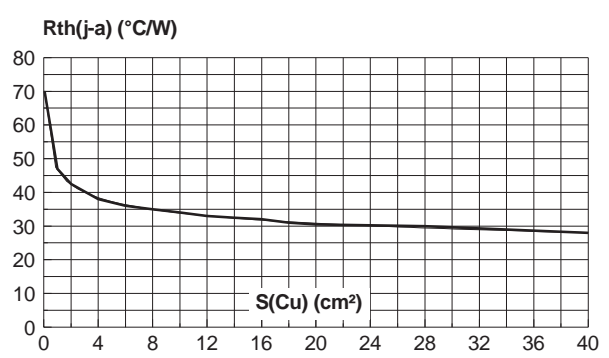
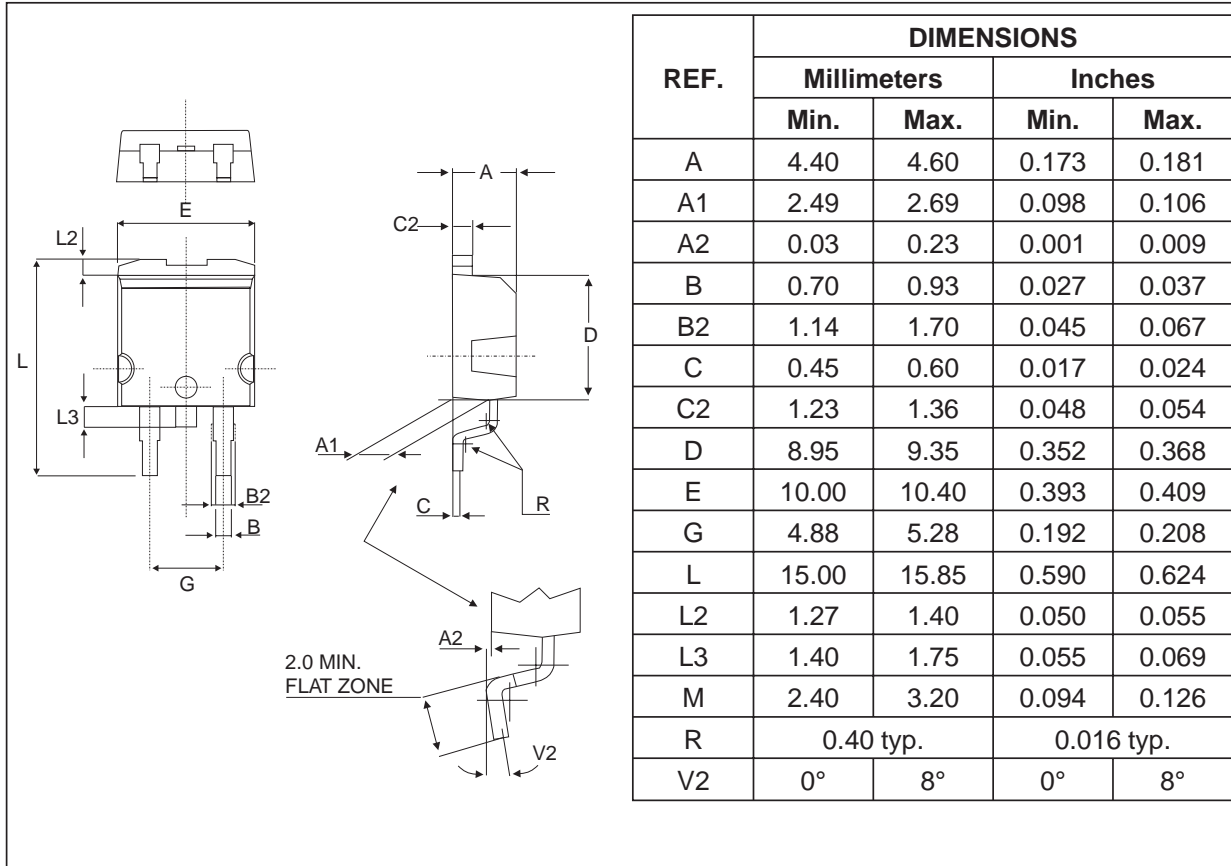


Fig. 10: Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board FR4, copper thickness : 35 μm). (STPS15L25G only)

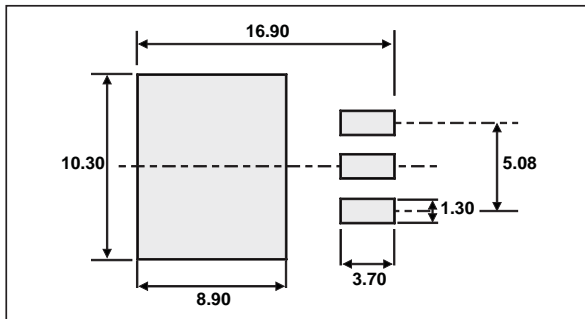


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PACKAGE MECHANICAL DATA
D²PAK



FOOT PRINT DIMENSIONS (in millimeters)

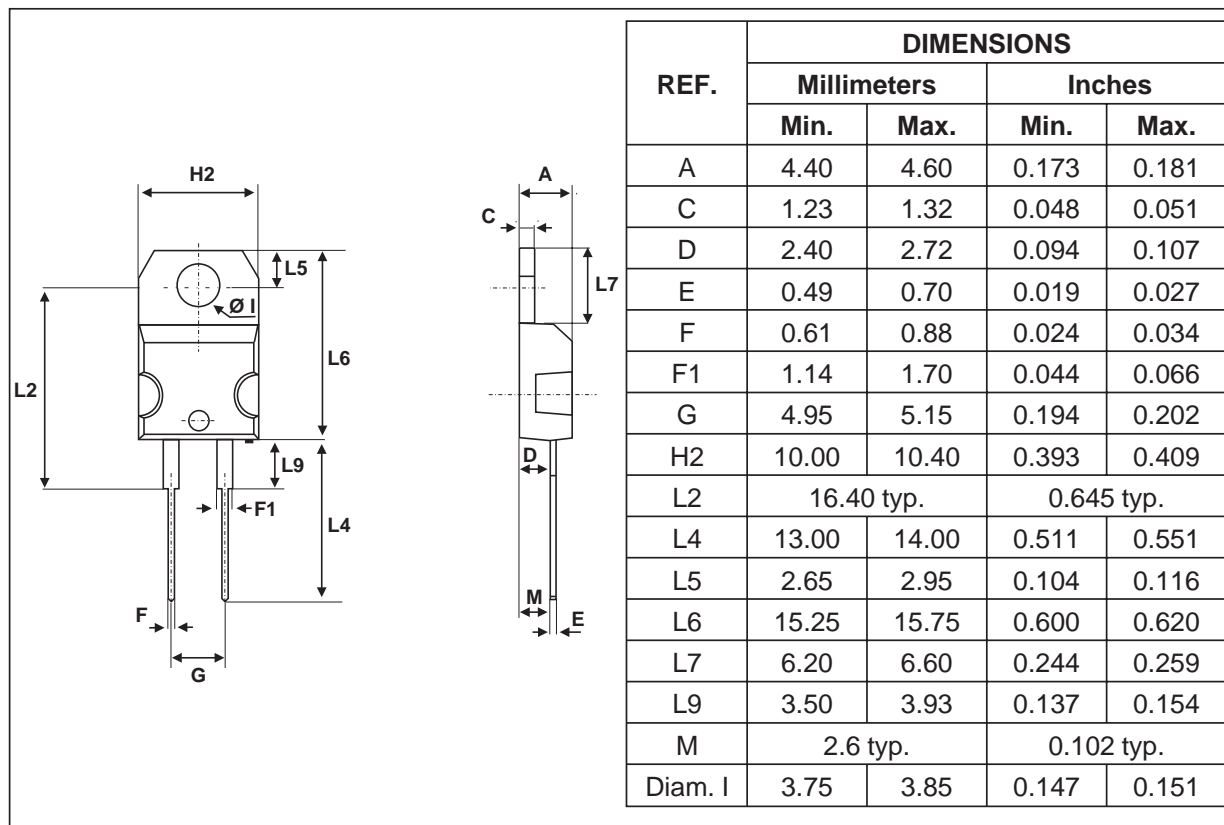


▪ COOLING METHOD: BY CONDUCTION (METHOD C)

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PACKAGE MECHANICAL DATA

TO-220AC



- COOLING METHOD : C
- RECOMMENDED TORQUE VALUE : 0.55 M.N
- MAXIMUM TORQUE VALUE : 0.70 M.N

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS15L25D	STPS15L25D	TO-220AC	1.86g	50	Tube
STPS15L25G	STPS15L25G	D ² PAK	1.48g	50	Tube
STPS15L25G-TR	STPS15L25G	D ² PAK	1.48g	1000	Tape & reel

- EPOXY MEETS UL94,V0

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